



ASE GROUP



# 日月光半導體 2016第二季法人說明會

吳田玉  
集團營運長

2016年7月29日

# 免責聲明



**This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this presentation. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the uncertainties as to whether we can complete the acquisition of 100% of Siliconware Precision Industries Co., Ltd. shares not otherwise owned by ASE; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2015 Annual Report on Form 20-F filed on April 29, 2016.**



# 日月光營運概況及業績展望

## ◦ 2016 第二季營運概況

- 廣泛的生意復甦，包括在通訊，消費性及汽車市場
- 日月光集團季營收成長百分之零點四，半導體封測事業季營收成長百分之八點三

## ◦ 2016 第三季業績展望

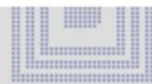
- 新產品上市帶動成長
- 產能將較前季增長百分之五，利用率也較前季提升百分之五

## ◦ 預期下半年日月光集團營收逐季成長

## ◦ 與矽品合組控股公司案之近況

謝謝

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# 日月光半導體 2016第二季法人說明會

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# Safe Harbor Notice



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# 合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2016	%	Q1 / 2016	%	季變化
營業收入淨額:					
封裝	30,178	48.2%	28,036	45.0%	8%
測試	6,503	10.4%	5,995	9.6%	8%
材料直接銷售	759	1.2%	892	1.4%	-15%
電子代工服務	24,845	39.7%	24,749	39.7%	0%
其它	316	0.5%	2,699	4.3%	-88%
營業收入淨額合計	62,601	100.0%	62,371	100.0%	0%
營業毛利	12,255	19.6%	11,449	18.4%	7%
營業淨利 (淨損)	5,931	9.5%	5,206	8.3%	14%
稅前淨利 (淨損)	6,473	10.3%	5,656	9.1%	14%
所得稅利益 (費用)	(1,523)	-2.4%	(1,318)	-2.1%	
非控制權益	(271)	-0.4%	(175)	-0.3%	
歸屬於本公司業主之淨利	4,679	7.5%	4,163	6.7%	12%
基本每股盈餘 (新台幣元)	0.61		0.54		13%
稀釋每股盈餘 (新台幣元)	0.51		0.43		19%
EBITDA	13,977	22.3%	13,229	21.2%	6%



# 合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2016	%	Q2 / 2015	%	年變化
營業收入淨額:					
封裝	30,178	48.2%	28,618	40.8%	5%
測試	6,503	10.4%	6,231	8.9%	4%
材料直接銷售	759	1.2%	839	1.2%	-10%
電子代工服務	24,845	39.7%	34,534	49.2%	-28%
其它	316	0.5%	0	0.0%	
營業收入淨額合計	62,601	100.0%	70,222	100.0%	-11%
營業毛利	12,255	19.6%	11,566	16.5%	6%
營業淨利 (淨損)	5,931	9.5%	5,409	7.7%	10%
稅前淨利 (淨損)	6,473	10.3%	5,400	7.7%	20%
所得稅利益 (費用)	(1,523)	-2.4%	(1,596)	-2.3%	
非控制權益	(271)	-0.4%	(152)	-0.2%	
歸屬於本公司業主之淨利	4,679	7.5%	3,652	5.2%	28%
基本每股盈餘 (新台幣元)	0.61		0.48		27%
稀釋每股盈餘 (新台幣元)	0.51		0.43		19%
EBITDA	13,977	22.3%	13,369	19.0%	5%





# 綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2016	%	Q1 / 2016	%	季變化
營業收入淨額:					
封裝	31,180	81.0%	28,597	80.5%	9%
測試	6,502	16.9%	5,995	16.9%	8%
材料直接銷售	801	2.1%	931	2.6%	-14%
其它	21	0.1%	20	0.1%	5%
營業收入淨額合計	38,504	100.0%	35,543	100.0%	8%
營業毛利	9,561	24.8%	7,832	22.0%	22%
營業淨利 (淨損)	4,957	12.9%	3,222	9.1%	54%
稅前淨利 (淨損)	6,001	15.6%	4,746	13.4%	26%
所得稅利益 (費用)	(1,266)	-3.3%	(529)	-1.5%	
非控制權益	(56)	-0.1%	(54)	-0.2%	
歸屬於本公司業主之淨利	4,679	12.2%	4,163	11.7%	12%
EBITDA	12,206	31.7%	10,580	29.8%	15%



# 綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)

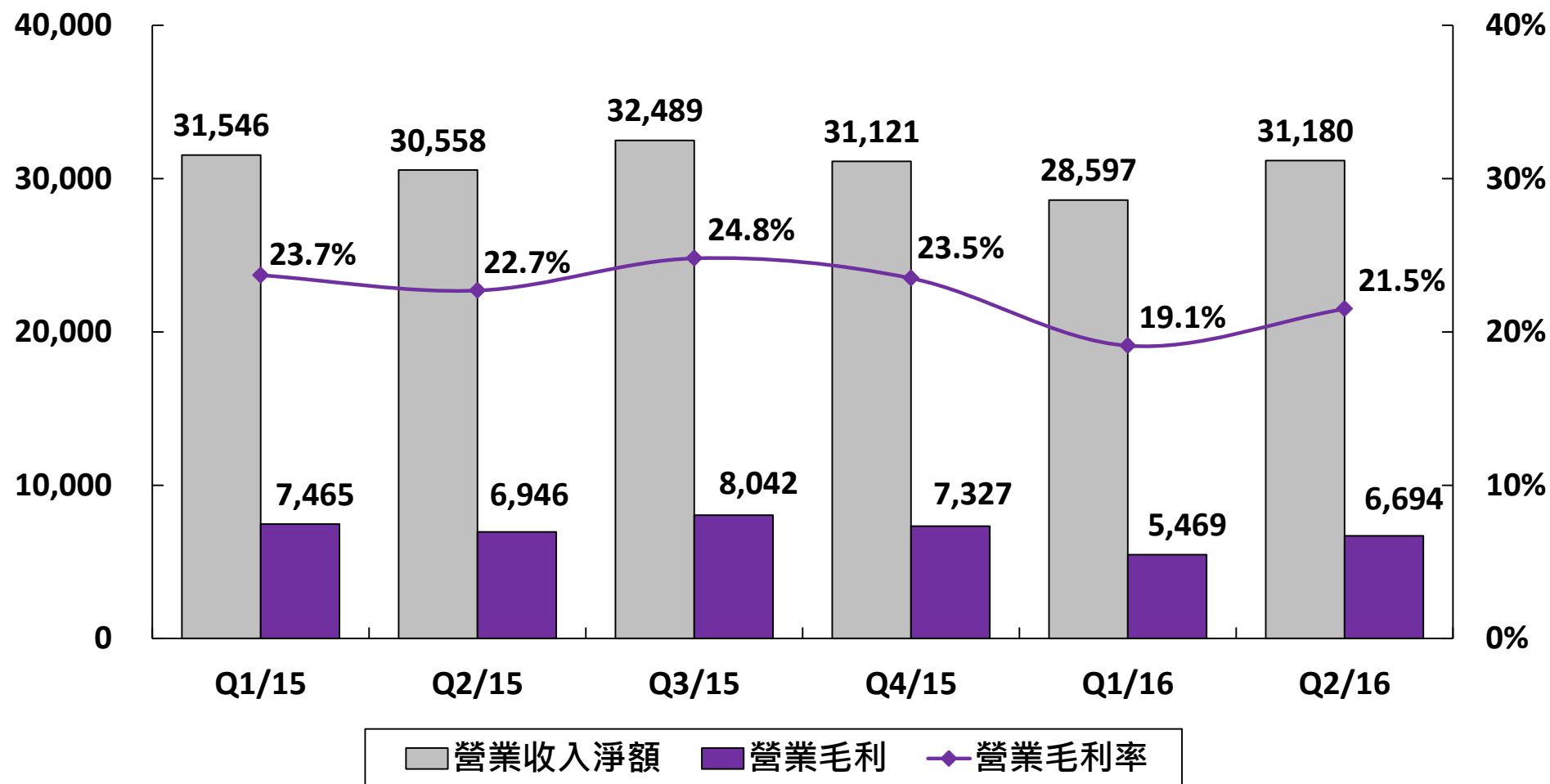


(新台幣百萬元)	Q2 / 2016	%	Q2 / 2015	%	年變化
營業收入淨額:					
封裝	31,180	81.0%	30,558	81.1%	2%
測試	6,502	16.9%	6,230	16.5%	4%
材料直接銷售	801	2.1%	865	2.3%	-7%
其它	21	0.1%	18	0.0%	17%
營業收入淨額合計	38,504	100.0%	37,671	100.0%	2%
營業毛利	9,561	24.8%	9,504	25.2%	1%
營業淨利 (淨損)	4,957	12.9%	5,101	13.5%	-3%
稅前淨利 (淨損)	6,001	15.6%	5,229	13.9%	15%
所得稅利益 (費用)	(1,266)	-3.3%	(1,537)	-4.1%	
非控制權益	(56)	-0.1%	(40)	-0.1%	
歸屬於本公司業主之淨利	4,679	12.2%	3,652	9.7%	28%
EBITDA	12,206	31.7%	11,620	30.8%	5%



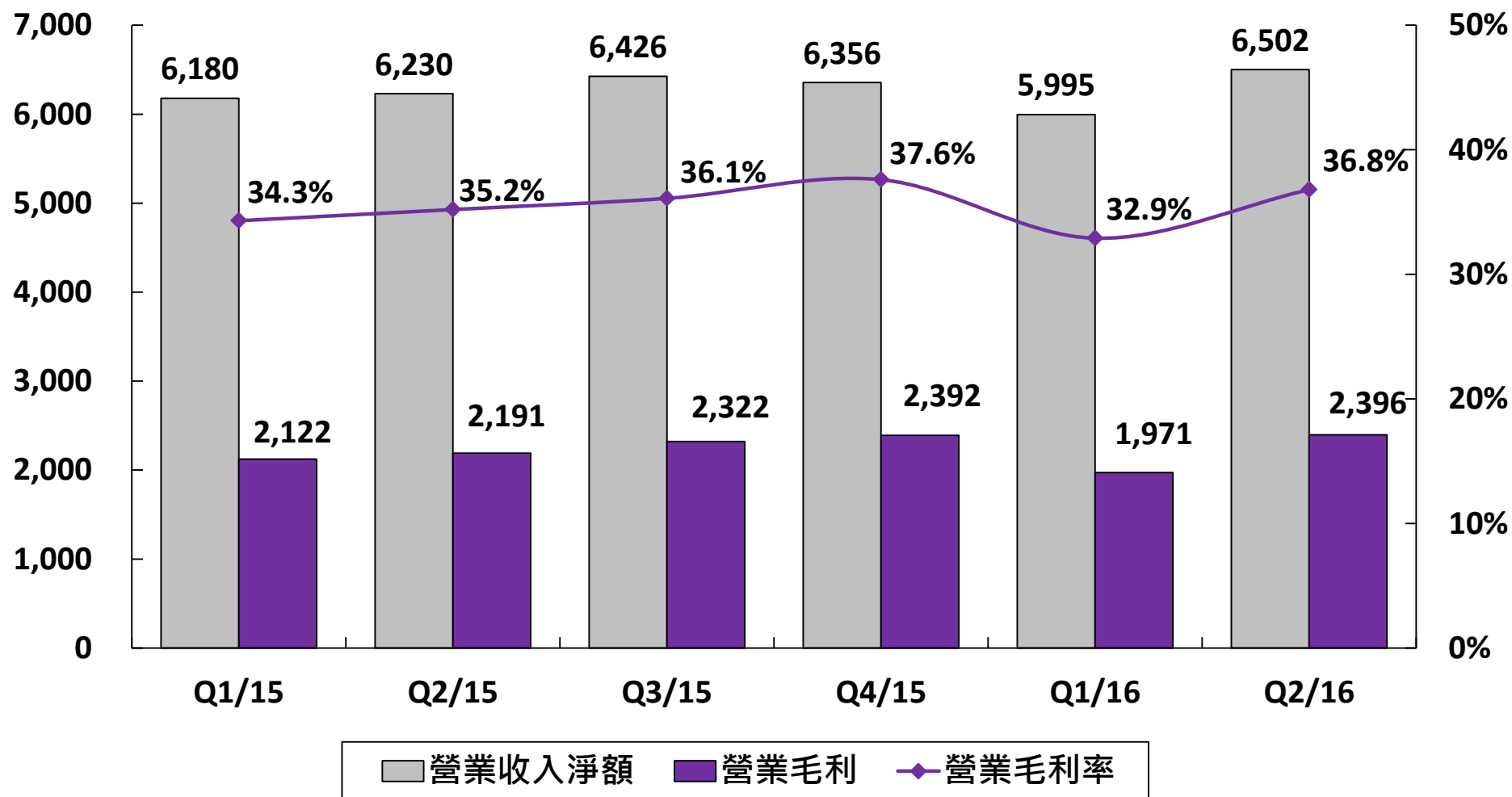
# 封裝業務

新台幣百萬元



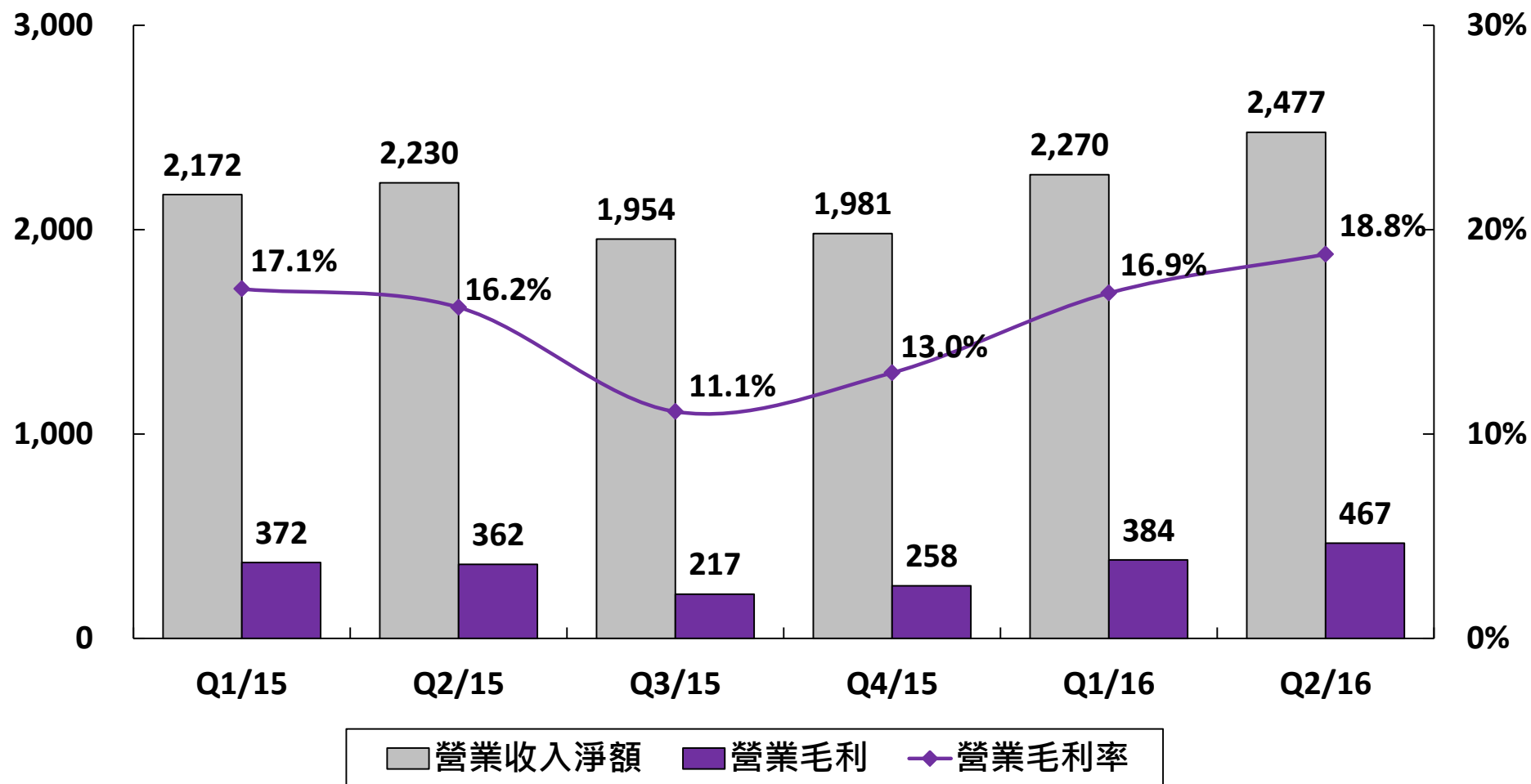
# 測試業務

新台幣百萬元



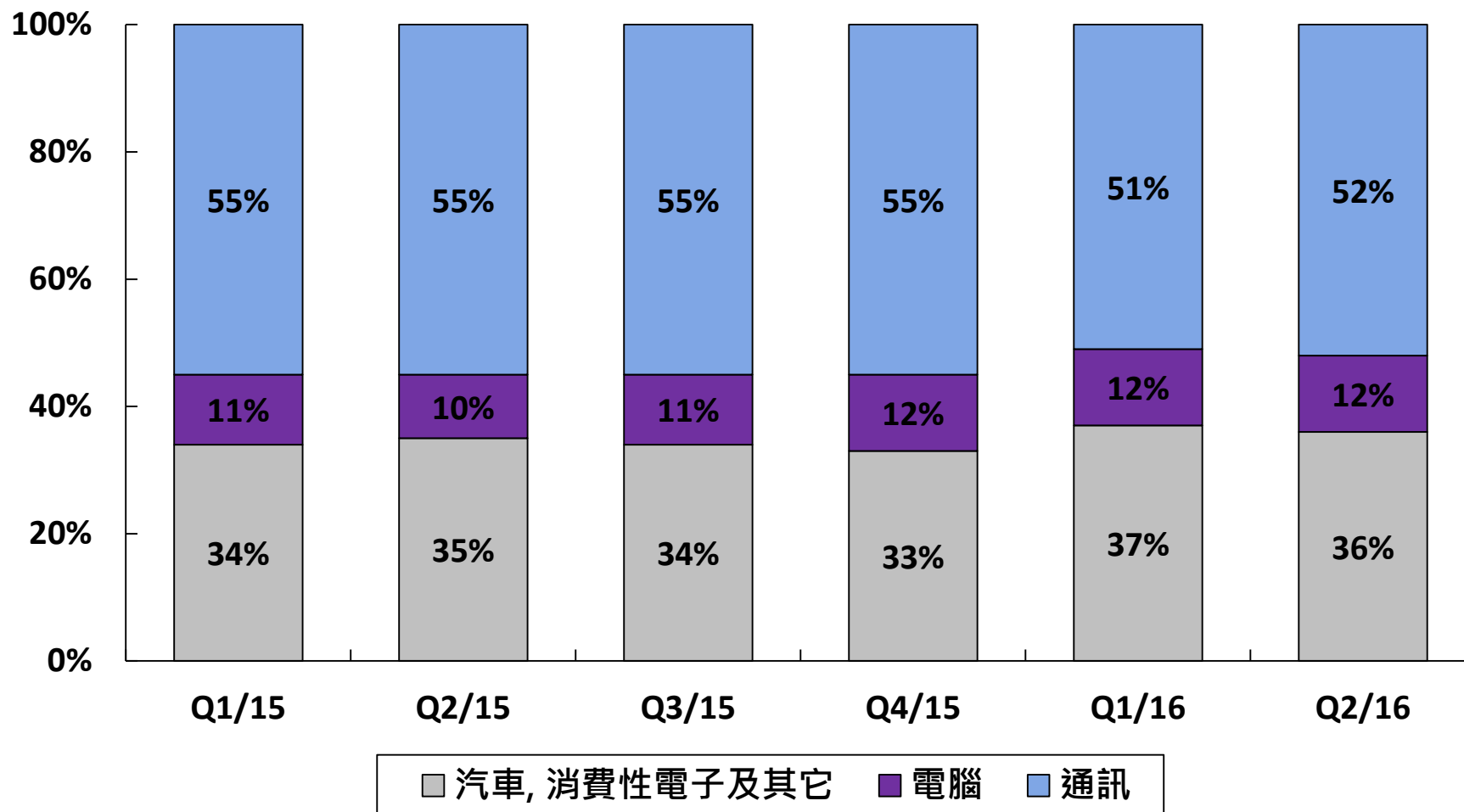
# 材料業務

新台幣百萬元



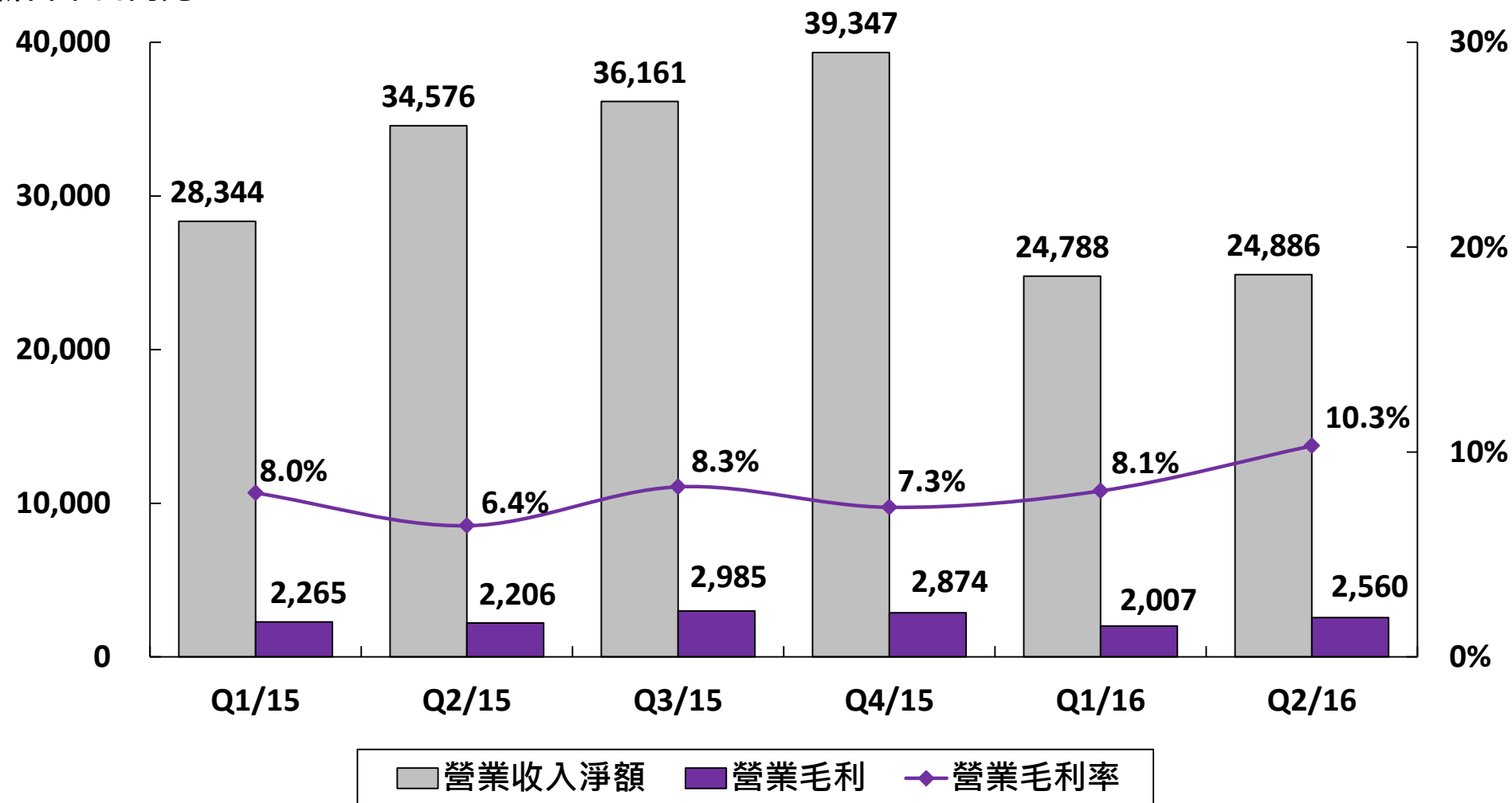
# 半導體封測營收

產品應用別佔比



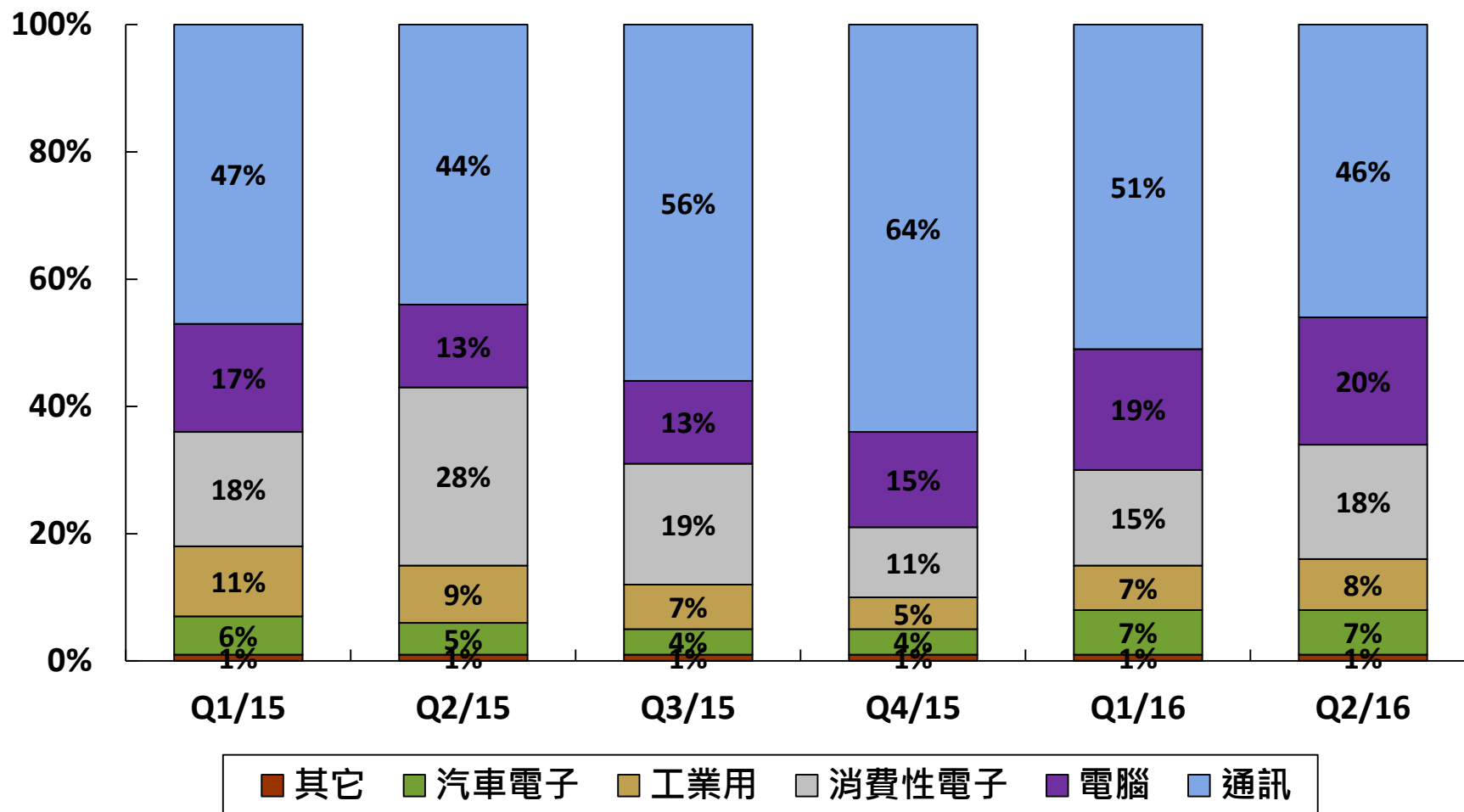
# 電子代工服務業務

新台幣百萬元



# 電子代工服務業務

產品應用別





# 重要資產負債表項目及財務指標

(未經會計師查核)



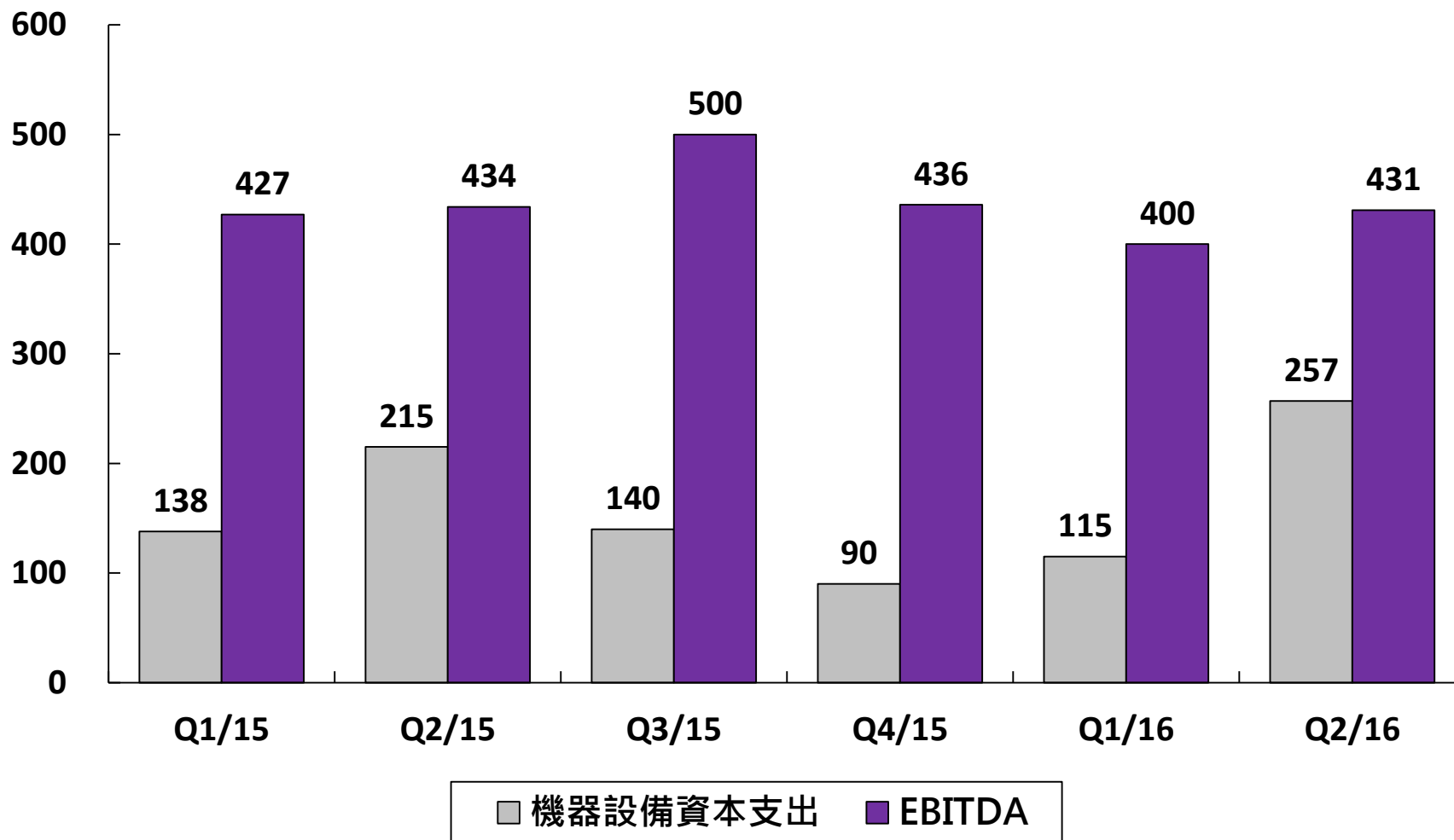
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(新台幣百萬元)	2016年6月30日	2016年3月31日	季變化
現金及約當現金	36,873	45,070	-18.2%
金融資產 - 流動	3,588	4,358	-17.7%
金融資產 - 非流動及採用權益法之投資	50,457	52,340	-3.6%
不動產、廠房及設備	147,650	147,234	0.3%
資產總計	354,942	356,490	-0.4%
短期借款及應付短期票券	18,319	34,154	-46.4%
一年內到期之應付公司債	22,550	14,482	55.7%
一年內到期之長期借款及應付租賃款	5,229	1,356	285.6%
應付公司債	24,652	32,582	-24.3%
長期借款及應付租賃款	39,664	36,089	9.9%
權益總計 (含非控制權益)	160,229	168,737	-5.0%
當季 EBITDA	13,977	13,229	5.7%
流動比率	1.13	1.25	
負債權益比率	0.44	0.41	



# 機器設備資本支出及EBITDA

美金百萬元



# 2016年第三季業績展望

根據對當前業務狀況的評估及匯率的假設，日月光公司2016年第三季的業績展望如下：

- 半導體封測事業產能將較前季增長百分之五
- 半導體封測事業利用率也將較前季提升百分之五
- 半導體封測事業毛利率與去年第四季水準相仿
- 電子代工服務生意量將會接近去年第二季水準
- 電子代工服務毛利率將會接近今年第一季水準



# Thank You

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